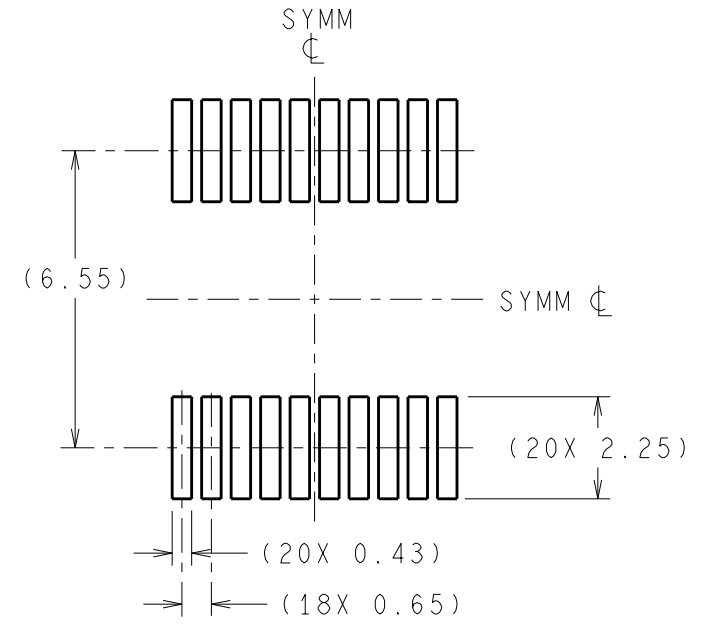
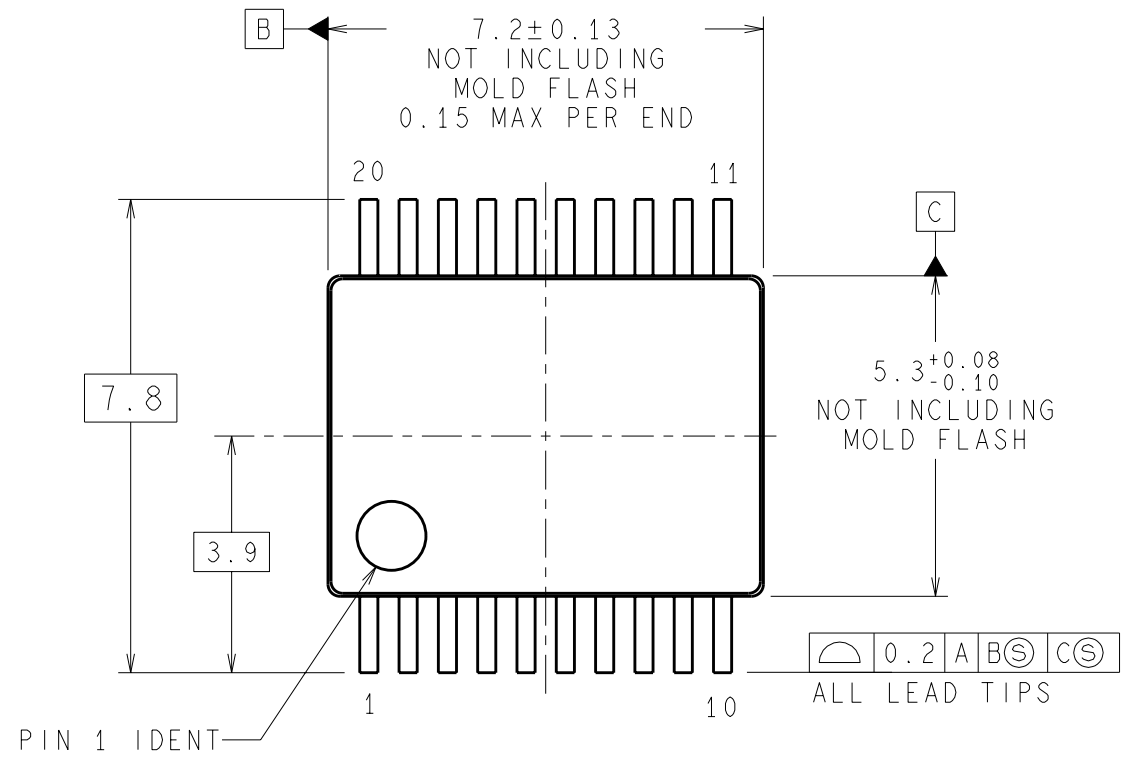
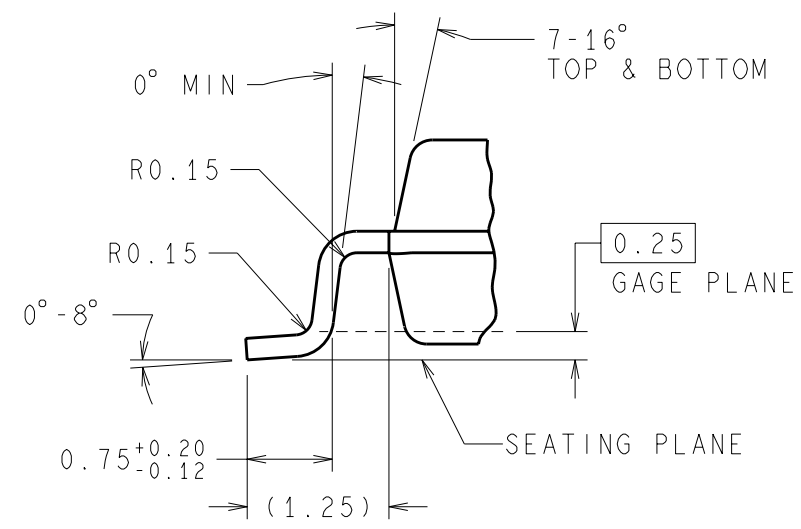
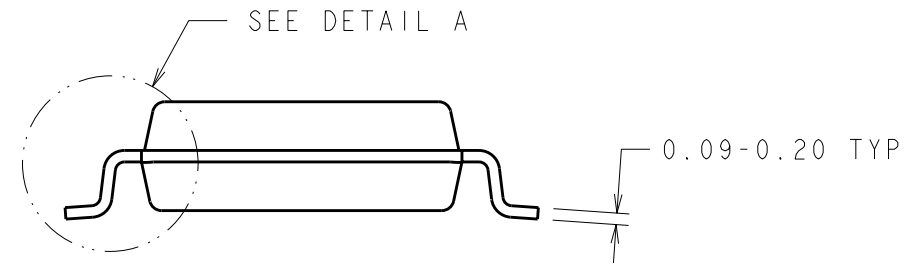
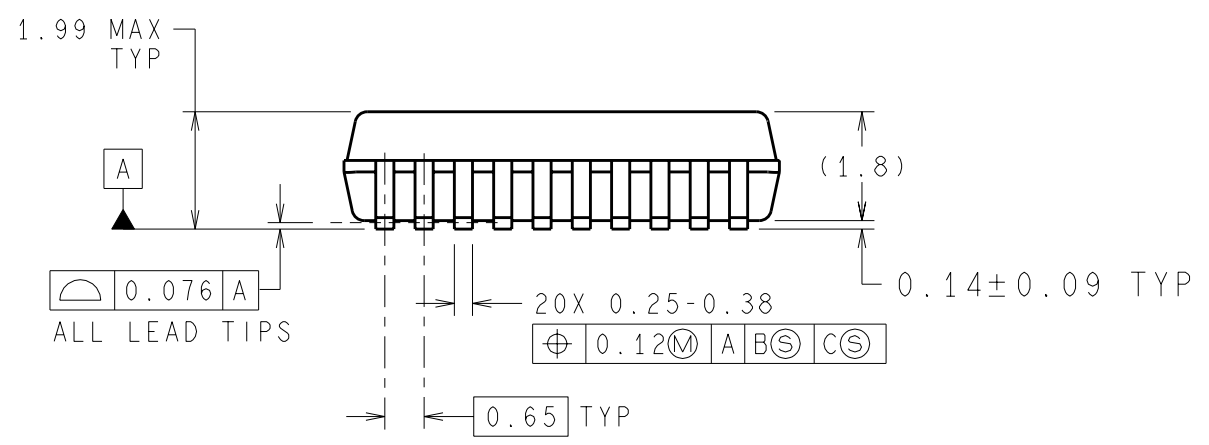


REVISIONS				
REV	DESCRIPTION	E.C.N.	DATE	BY/APP'D
B	REVISE & REDRAW PER CURRENT STANDARDS; ADD LAND PATTERN RECOMMENDATION	123	07/12/2000	TL/CD
C	CHANGE DRAFT ANGLE TO 7-16°; WAS 12-16° CHANGE STANDOFF TO 0.14±0.09; WAS 0.15±0.08 ADD NOTE ON LEAD FINISH, MOLD FLASH, AND JEDEC REGISTRATION ADD NOTE "DIMENSIONS IN () FOR REFERENCE ONLY" UPDATE DIMENSIONS ON LAND PATTERN USE ACTUAL NUMBER OF LEADS INSTEAD OF TYP	2904	10/06/2009	TKY/EL/SYL



LAND PATTERN RECOMMENDATION



DETAIL A
TYPICAL

DIMENSIONS ARE IN MILLIMETERS
DIMENSIONS IN () FOR REFERENCE ONLY

NOTES: UNLESS OTHERWISE SPECIFIED

1. FOR LEAD FINISH THICKNESS AND COMPOSITION, SEE "SOLDER INFORMATION" IN PACKAGING SECTION OF THE NATIONAL SEMICONDUCTOR WEB PAGE (www.national.com)
2. REFERENCE JEDEC REGISTRATION MO-150, VARIATION AE.

APPROVALS		DATE	 2900 Semiconductor Dr., Santa Clara, CA 95052-8090
DRAWN	T. LEQUANG	07/12/2000	
DFTG. CHK.	EUGENE LEE	10/06/2009	
ENGR. CHK.	SY LONG	10/06/2009	
MOLDDED SSOP, 5.3mm BODY WIDTH, 0.65mm PITCH, EIAJ, TYPE II, 20 LEAD			
PROJECTION	SCALE	SIZE	DRAWING NUMBER
 MM	NTS	B	(SC)MKT-MSA20
FORMERLY: N/A			REV C
SHEET 1 of 1			